

N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

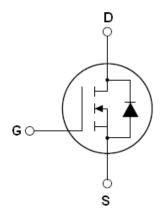
Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS}	650	V
R _{DS(ON)TYP.}	950	mΩ
I_D	4	A



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65T1K2	TO-220	NCE65T1K2
NCE65T1K2D	TO-263	NCE65T1K2D
NCE65T1K2F	TO-220F	NCE65T1K2F







TO-263

TO-220

TO-220F

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	NCE65T1K2 NCE65T1K2D	NCE65T1K2F	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	650		V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	V _G S	土	30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	4	4*	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	2.5	2.5*	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	16	16*	Α
Maximum Power Dissipation(Tc=25℃)	P _D	41	28.4	W
Derate above 25°C		0.328	0.227	w/°C
Single pulse avalanche energy (Note2)	Eas	27		mJ
Avalanche current ^(Note 1)	I _{AR}	0.7		Α
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	0.1		mJ

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Parameter	Symbol	NCE65T1K2 NCE65T1K2D	NCE65T1K2F	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50		V/ns
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15		V/ns
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55	+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE65T1K2 NCE65T1K2D	NCE65T1K2F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	3.0	4.4	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25℃ unless otherwise noted)

Table 3. Electrical Characteristics (TA-25 Curiless otherwise noted)						
Parameter	Symbol	Symbol Condition		Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			50	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	3		4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =2A		950	1100	mΩ
Dynamic Characteristics			•			
Input Capacitance	C _{lss}	\/ 50\/\\ 0\/		304		pF
Output Capacitance	C _{oss}	V_{DS} =50V, V_{GS} =0V, F=1.0MHz		18		pF
Reverse Transfer Capacitance	C _{rss}	F=1.UNIFIZ		0.6		pF
Total Gate Charge	Qg			8.8	12	nC
Gate-Source Charge	Q_{gs}	V _{DS} =480V,I _D =4A,		2.3		nC
Gate-Drain Charge	Q_{gd}	- V _{GS} =10V		4		nC
Switching times			•			
Turn-on Delay Time	t _{d(on)}			8		nS
Turn-on Rise Time	t _r	V _{DD} =380V,I _D =2.5A,		4		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=5\Omega, V_{GS}=10V$		52	70	nS
Turn-Off Fall Time	t _f			9	18	nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I _{SD}	T -25°C			4	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			16	Α
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =4A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}			200		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =2A,di/dt=100A/µs		0.6		uC
Peak reverse recovery current	I _{rrm}			6		Α

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

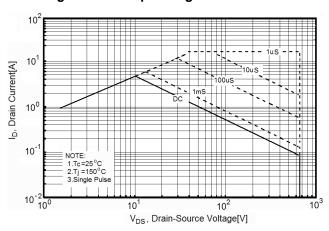


Figure 2. Source-Drain Diode Forward Voltage

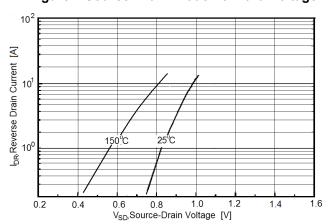


Figure 3. Output characteristics

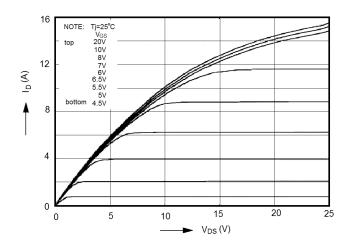


Figure 4. Transfer characteristics

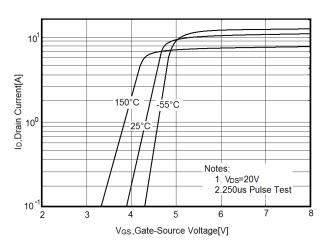


Figure 5. Static drain-source on resistance

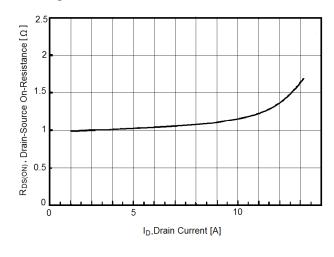
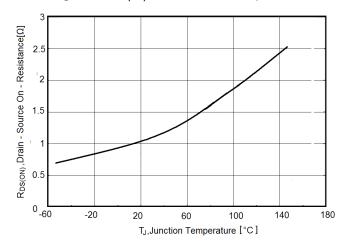


Figure 6. R_{DS(ON)} vs Junction Temperature



v1.0



Figure 7. BV_{DSS} vs Junction Temperature

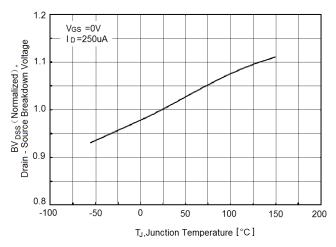


Figure 9. Gate charge waveforms

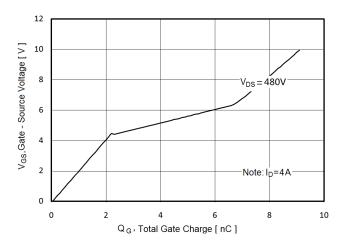


Figure 11. Transient Thermal Impedance for TO-220, TO-263

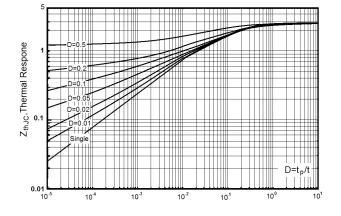


Figure 8. Maximum I_D vs Junction Temperature

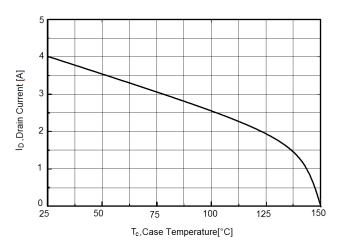


Figure 10. Capacitance

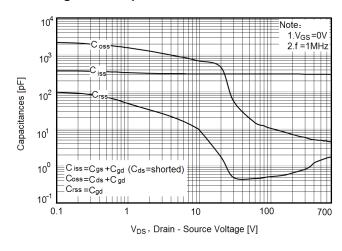


Figure 12. Safe operating area for TO-220F

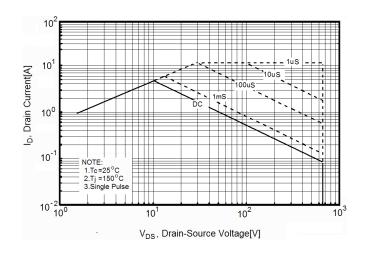
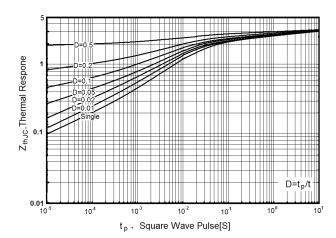




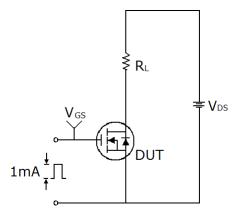
Figure 13. Transient Thermal Impedance for TO-220F

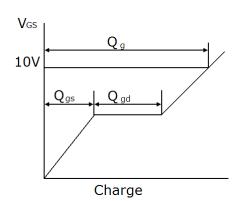




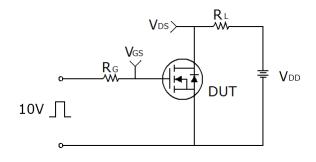
Test circuit

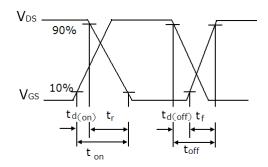
1) Gate charge test circuit & Waveform



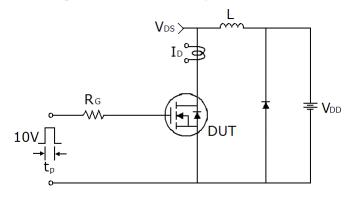


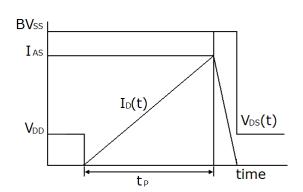
2) Switch Time Test Circuit:





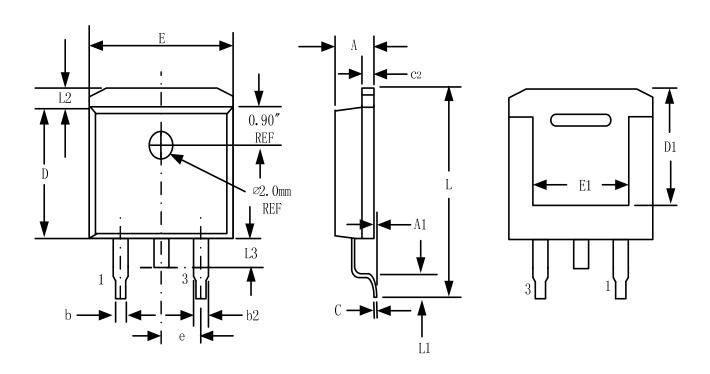
3) Unclamped Inductive Switching Test Circuit & Waveforms







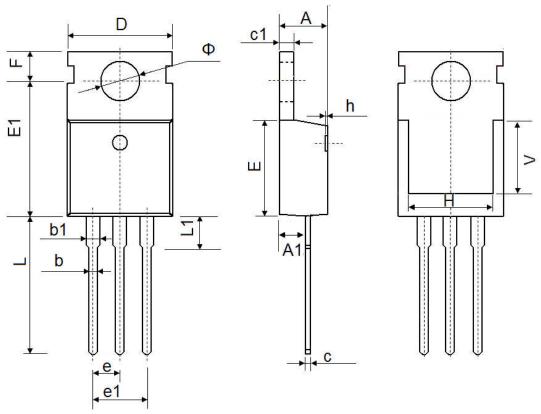
TO-263-3L Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.32	4.57	0.170	0.180	
A1	-	0.25		0.010	
b	0.71	0.94	0.028	0.037	
b2	1.15	1.40	0.045	0.055	
С	0.46	0.61	0.018	0.024	
c2	1.22	1.40	0.048	0.055	
D	8.89	9.40	0.350	0.370	
D1	8.01	8.23	0.315	0.324	
E	10.04	10.28	0.395	0.405	
E1	7.88	8.08	0.310	0.318	
е	2.54	2.54 BSC		BSC	
L	14.73	15.75	0.580	0.620	
L1	2.29	2.79	0.090	0.110	
L2	1.15	1.39	0.045	0.055	
L3	1.27	1.77	0.050	0.070	



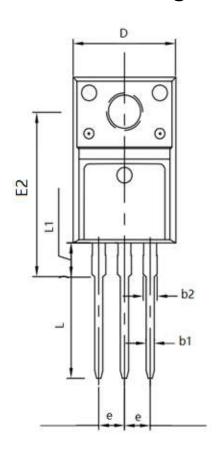
TO-220-3L-C Package Information

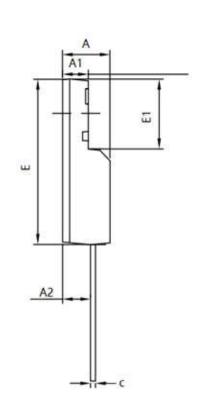


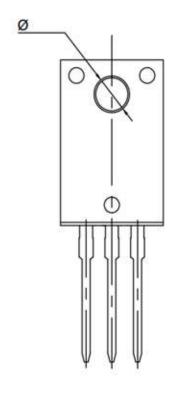
Comple al	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.54	0 TYP.	0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.50	0 REF.	0.295	REF.	
Ф	3.400	3.800	0.134	0.150	



TO-220F Package Information







Symbol	Dimensions I	n Millimeters	Dimension	s In Inches
	Min.	Max.	Min.	Max.
Α	4.500	4.900	0.177	0.193
A1	2.340	2.740	0.092	0.108
A2	2.560	2.960	0.101	0.117
b1	0.700	0.900	0.028	0.035
b2	1.180	1.580	0.046	0.062
С	0.400	0.600	0.016	0.024
D	9.960	10.360	0.392	0.408
Е	15.670	15.970	0.617	0.629
E1	6.500	6.900	0.256	0.272
E2	15.500	16.100	0.610	0.634
е	2.540 TYP		0.100) TYP
Ф	3.080	3.280	0.121	0.129
L	12.640	13.240	0.498	0.521
L1	3.030	3.430	0.119	0.135



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